

WAYNE - THIS MODIFICATION HAS  
BEEN DONE

## TU - 300 USERS NEWSLETTER

August 11, 1982

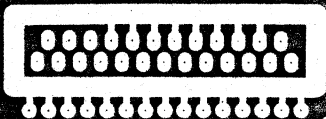
SUBJECT: Modification to improve MARK HOLD and ANTI-SPACE.

The un-modified TU-300 will turn the relay on with a space signal, and with high audio gain, garble has been experienced when going from xmit to rec.. With the addition of these parts, tacked onto the solder side of the board, this situation should be corrected. Attached to this newsletter is a solder side MAIN BOARD layout and a schematic showing these additions to the existing circuit.

1. Remove the cover and lay the unit on it's top so as to expose the solder side of the main board. (Make sure the AC is not connected before removing cover.)
2. Locate IC3 pin 5 and with a razor blade, cut the pad free from the line running past the IC pins.
3. Refer to the MAIN BOARD layout sheet supplied with these instructions, make the other two cuts to as shown.
4. The solder mask will have to be scraped off of the line where components have to be attached in order for the solder to take hold.
5. Install the components as shown on the MAIN BOARD foil layout, mounting them as flush to the board as possible.
6. Check for solder bridges, shorted leads and polarity. If everything looks good, replace the cover and have fun.

4- 11/11/82  
2- 11/11/82  
1- 11/11/82

335 103 B



~~CUT FOIL  
BETWEEN  
PAD & LINE~~

~~1 $\mu$ F CAP~~

~~DIODE  
1N4148~~

~~RESISTOR  
8.2 MEG  
1/4 watt~~

~~RESISTOR  
8.2 MEG  
1/4 watt~~

~~DIODE  
1N4148~~

~~DIODE  
1N4148~~

~~CUT  
FOIL HERE~~

